

EMIF07-LCD02F3

7-line IPAD™, EMI filter and ESD protection for LCD and cameras

Features

- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering
- Lead-free package
- Very low PCB space occupation: 1.94 mm x 1.54 mm
- Very thin package: 0.65 mm
- High efficiency in ESD suppression
- High reliability offered by monolithic integration
- High reduction of parasitic elements through integration and wafer level packaging

Complies with the following standards

- IEC 61000-4-2 level 4 on inputs and outputs:
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883G Method 3015-7 Class 3

Applications

Where EMI filtering in ESD sensitive equipment is required:

- LCD for mobile phones
- Computers and printers
- Communication systems
- MCU boards

Description

The EMIF07-LCD02F3 is a 7-line highly integrated device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interference. The EMIF07 Flip Chip package means the package size is equal to the die size.

This filter includes ESD protection circuitry, which prevents damage to the protected device when subjected to ESD surges up 15 kV.

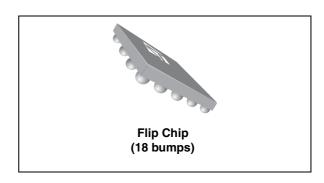


Figure 1. Pin layout (bump side)

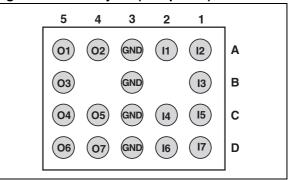
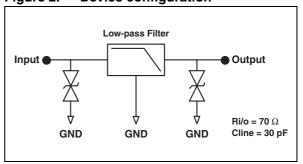


Figure 2. Device configuration



TM: IPAD is a trademark of STMicroelectronics.

Characteristics EMIF07-LCD02F3

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25$ °C)

| Symbol | Parameter and test conditions | Value | Unit |
|------------------|-------------------------------|------------|------|
| T _j | Maximum junction temperature | 125 | °C |
| T _{op} | Operating temperature range | -40 to +85 | °C |
| T _{stg} | Storage temperature range | -55 to 150 | °C |

Table 2. Electrical characteristics ($T_{amb} = 25$ °C)

| Symbol | Parameters | | | | | |
|-------------------|---|--|-----|-----|-----|------|
| V_{BR} | Breakdown voltage | ↑ | | | | |
| I _{RM} | Leakage current @ V _{RM} | V _{CL} V _{BR} V _{RM} V _F V _F V I _{RM} I _R I | | | | |
| V_{RM} | Stand-off voltage | | | | | |
| V_{CL} | Clamping voltage | | | 1 | | |
| I _{PP} | Peak pulse current | | | | | |
| R _{I/O} | Series resistance between input and output | | | | | |
| C _{line} | Input capacitance per line | | | | | |
| Symbol | Test conditions | | Min | Тур | Max | Unit |
| V _{BR} | I _R = 1 mA | | 6 | 8 | 10 | V |
| I _{RM} | V _{RM} = 3 V | | | 50 | 200 | nA |
| R ₂ | Tolerance ± 20% | | | 70 | | Ω |
| C _{line} | Vline = 0 V, V _{OSC} = 30 mV, F =1 MHz | | | | 30 | pF |

EMIF07-LCD02F3 Characteristics

Figure 3. Attenuation measurement and Aplac simulation

Figure 4. Analog cross talk measurement

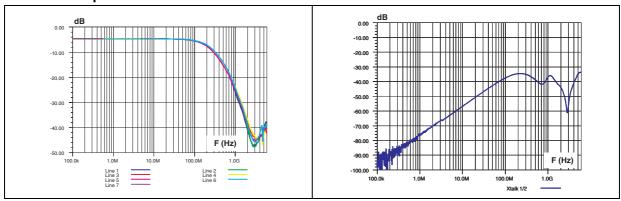


Figure 5. Voltages when IEC 61000-4-2 (+15 kV air discharge) applied to input pin

Figure 6. Voltages when IEC 61000-4-2 (-15 kV air discharge) applied to input pin

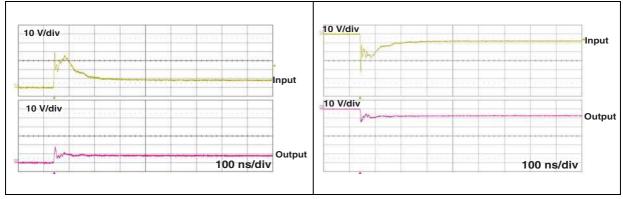
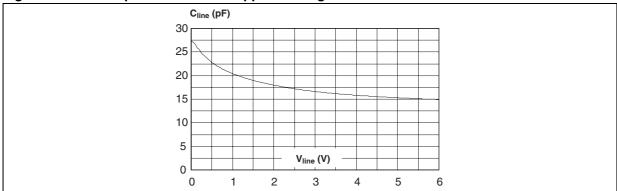


Figure 7. Line capacitance versus applied voltage



2 Application information

Figure 8. Aplac model

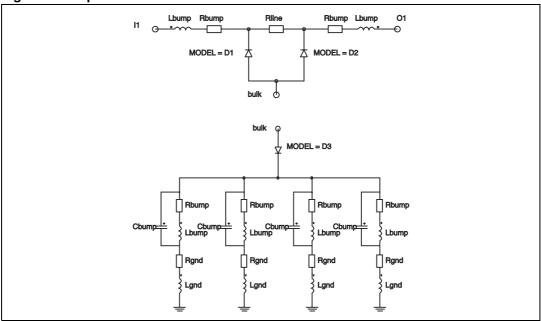
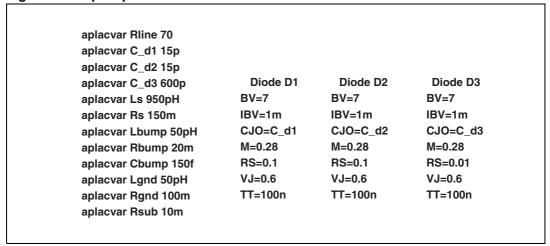
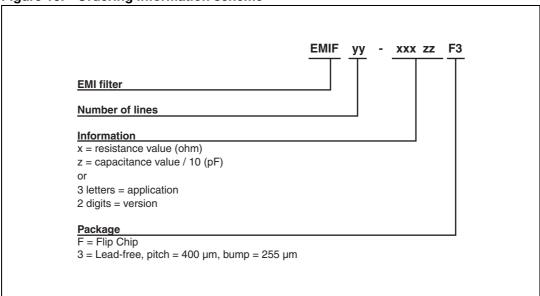


Figure 9. Aplac parameters



3 Ordering information scheme

Figure 10. Ordering information scheme



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

Figure 11. Package dimensions

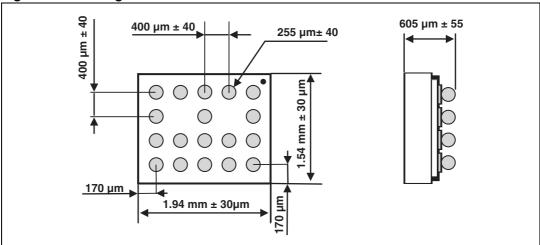


Figure 12. Footprint

Figure 13. Marking

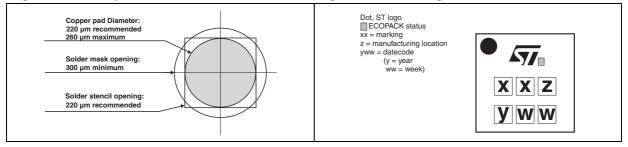
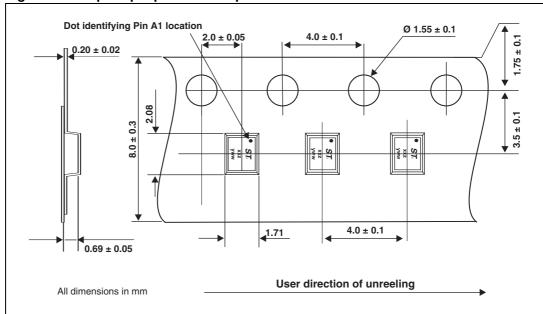


Figure 14. Flip Chip tape and reel specification



Note: More information is available in the application notes:

AN2348: "STMicroelectronics 400 micro-metre Flip Chip: Package description and recommendation for use"

AN1751: "EMI filters: Recommendations and measurements"

5 Ordering information

Table 3. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|----------------|---------|-----------|--------|----------|------------------|
| EMIF07-LCD02F3 | GX | Flip Chip | 3.9 mg | 5000 | Tape and reel 7" |

EMIF07-LCD02F3 Revision history

6 Revision history

Table 4. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 12-Sep-2005 | 1 | First issue. |
| 28-Apr-2008 | 2 | Updated ECOPACK statement. Updated Figure 10, Figure 11 and Figure 14. Reformatted to current standards. |
| 19-Feb-2010 | 3 | Updated die size in Figure 11. |

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